

Sung Kyu Lim

Design for High Performance, Low Power, and Reliable 3D Integrated Circuits

 Springer

Design For High Performance Low Power And Reliable 3d Integrated Circuits

L Cohen



Design For High Performance Low Power And Reliable 3d Integrated Circuits:

Design for High Performance, Low Power, and Reliable 3D Integrated Circuits Sung Kyu Lim, 2012-11-27 This book provides readers with a variety of algorithms and software tools dedicated to the physical design of through silicon via TSV based three dimensional integrated circuits It describes numerous manufacturing ready GDSII level layouts of TSV based 3D ICs developed with the tools covered in the book This book will also feature sign off level analysis of timing power signal integrity and thermal analysis for 3D IC designs Full details of the related algorithms will be provided so that the readers will be able not only to grasp the core mechanics of the physical design tools but also to be able to reproduce and improve upon the results themselves This book will also offer various design for manufacturability DFM design for reliability DFR and design for testability DFT techniques that are considered critical to the physical design process

Handbook of Approximation Algorithms and Metaheuristics Teofilo F. Gonzalez, 2018-05-15 Handbook of Approximation Algorithms and Metaheuristics Second Edition reflects the tremendous growth in the field over the past two decades Through contributions from leading experts this handbook provides a comprehensive introduction to the underlying theory and methodologies as well as the various applications of approximation algorithms and metaheuristics Volume 1 of this two volume set deals primarily with methodologies and traditional applications It includes restriction relaxation local ratio approximation schemes randomization tabu search evolutionary computation local search neural networks and other metaheuristics It also explores multi objective optimization reoptimization sensitivity analysis and stability Traditional applications covered include bin packing multi dimensional packing Steiner trees traveling salesperson scheduling and related problems Volume 2 focuses on the contemporary and emerging applications of methodologies to problems in combinatorial optimization computational geometry and graphs problems as well as in large scale and emerging application areas It includes approximation algorithms and heuristics for clustering networks sensor and wireless communication bioinformatics search streams virtual communities and more About the Editor Teofilo F Gonzalez is a professor emeritus of computer science at the University of California Santa Barbara He completed his Ph D in 1975 from the University of Minnesota He taught at the University of Oklahoma the Pennsylvania State University and the University of Texas at Dallas before joining the UCSB computer science faculty in 1984 He spent sabbatical leaves at the Monterrey Institute of Technology and Higher Education and Utrecht University He is known for his highly cited pioneering research in the hardness of approximation for his sublinear and best possible approximation algorithm for k tMM clustering for introducing the open shop scheduling problem as well as algorithms for its solution that have found applications in numerous research areas as well as for his research on problems in the areas of job scheduling graph algorithms computational geometry message communication wire routing etc

3D Stacked Chips Ibrahim (Abe) M. Elfadel, Gerhard Fettweis, 2016-05-11 This book explains for readers how 3D chip stacks promise to increase the level of on chip integration and to design new

heterogeneous semiconductor devices that combine chips of different integration technologies incl sensors in a single package of the smallest possible size The authors focus on heterogeneous 3D integration addressing some of the most important challenges in this emerging technology including contactless optics based and carbon nanotube based 3D integration as well as signal integrity and thermal management issues in copper based 3D integration Coverage also includes the 3D heterogeneous integration of power sources photonic devices and non volatile memories based on new materials systems

Physical Design for 3D Integrated Circuits Aida Todri-Sanial, Chuan Seng Tan, 2017-12-19 Physical Design for 3D Integrated Circuits reveals how to effectively and optimally design 3D integrated circuits ICs It also analyzes the design tools for 3D circuits while exploiting the benefits of 3D technology The book begins by offering an overview of physical design challenges with respect to conventional 2D circuits and then each chapter delivers an in depth look at a specific physical design topic This comprehensive reference Contains extensive coverage of the physical design of 2 5D 3D ICs and monolithic 3D ICs Supplies state of the art solutions for challenges unique to 3D circuit design Features contributions from renowned experts in their respective fields Physical Design for 3D Integrated Circuits provides a single convenient source of cutting edge information for those pursuing 2 5D 3D technology

A Fresh Concept of Software-resemblant Hardware to Leap to 6G and Future Networks Jacopo Iannacci, 2024-04-01 For a decade with the uptake of 4G we have become accustomed to the relentless increase in data and services on the move The deployment of 5G is advancing crucial key performance indicators KPIs along with quality of service QoS Setting the horizon to 2030 and later 6G will take the KPIs to numbers 100 1000 times better than 5G Yet the actual disruption of 6G and future networks FN will take place following other unprecedented paths Artificial intelligence AI will be exploited in a threadlike fashion at any level of the network physical infrastructure This will introduce to date unknown features like self sustaining self evolution and high resilience of small portions of the infrastructure pioneering the concept of a network of networks Each segment of the infrastructure will bear a high degree of independence while working at the same time as a whole in full orchestration with the rest of the network Given such a scenario this book claims that the established and currently in use paradigms for the design and development of hardware software HW SW systems are not appropriate to address the challenges of 6G and further ahead of FN In response unprecedented design approaches are suggested relying on a fresh reinterpretation of the standard concept of HW with specific attention to the network edge and edge intelligence EI This work develops some conceptual tools that may help address the technical challenges resulting from the intricate scenario sketched above Within the mentioned HW reconceptualization a pivotal role is forecasted for microtechnologies and nanotechnologies intended with a broad meaning which embraces among others devices systems MEMS NEMS and materials

Electronic Design Automation for IC Implementation, Circuit Design, and Process Technology Luciano Lavagno, Igor L. Markov, Grant Martin, Louis K. Scheffer, 2017-02-03 The second of two volumes in the Electronic Design Automation for Integrated Circuits

Handbook Second Edition Electronic Design Automation for IC Implementation Circuit Design and Process Technology thoroughly examines real time logic RTL to GDSII a file format used to transfer data of semiconductor physical layout design flow analog mixed signal design physical verification and technology computer aided design TCAD Chapters contributed by leading experts authoritatively discuss design for manufacturability DFM at the nanoscale power supply network design and analysis design modeling and much more New to This Edition Major updates appearing in the initial phases of the design flow where the level of abstraction keeps rising to support more functionality with lower non recurring engineering NRE costs Significant revisions reflected in the final phases of the design flow where the complexity due to smaller and smaller geometries is compounded by the slow progress of shorter wavelength lithography New coverage of cutting edge applications and approaches realized in the decade since publication of the previous edition these are illustrated by new chapters on 3D circuit integration and clock design Offering improved depth and modernity Electronic Design Automation for IC Implementation Circuit Design and Process Technology provides a valuable state of the art reference for electronic design automation EDA students researchers and professionals

Solid-State Radiation Detectors Salah Awadalla, 2017-12-19 Integrating aspects of engineering application physics and medical science Solid State Radiation Detectors Technology and Applications offers a comprehensive review of new and emerging solid state materials based technologies for radiation detection Each chapter is structured to address the current advantages and challenges of each material and technology presented as well as to discuss novel research and applications Featuring contributions from leading experts in industry and academia this authoritative text Covers modern semiconductors used for radiation monitoring Examines CdZnTe and CdTe technology for imaging applications including three dimensional capability detectors Highlights interconnect technology for current pixel detectors Describes hybrid pixel detectors and their characterizations Tackles the integrated analog signal processing read out front ends for particle detectors Considers new organic materials with direct bandgap for direct energy detection Summarizes recent developments involving lanthanum halide and cerium bromide scintillators Analyzes the potential of recent progress in the field of crystallogenes quantum dots and photonics crystals toward a new concept of x and gamma ray detectors based on metamaterials Explores position sensitivity photomultipliers and silicon photomultipliers for scintillation crystals Solid State Radiation Detectors Technology and Applications provides a valuable reference for engineers and scientists looking to enhance the performance of radiation detector technology for medical imaging and other applications

Analog Electronics for Radiation Detection Renato Turchetta, 2017-12-19 Analog Electronics for Radiation Detection showcases the latest advances in readout electronics for particle or radiation detectors Featuring chapters written by international experts in their respective fields this authoritative text Defines the main design parameters of front end circuitry developed in microelectronics technologies Explains the basis for the use of complementary metal oxide semiconductor CMOS image sensors for the detection of charged particles and other non consumer applications Delivers an

in depth review of analog to digital converters ADCs evaluating the pros and cons of ADCs integrated at the pixel column and per chip levels Describes incremental sigma delta ADCs time to digital converter TDC architectures and digital pulse processing techniques complementary to analog processing Examines the fundamental parameters and front end types associated with silicon photomultipliers used for single visible light photon detection Discusses pixel sensors with per pixel TDCs channel density challenges and emerging 3D technologies interconnecting detectors and electronics Thus Analog Electronics for Radiation Detection provides a single source for state of the art information on analog electronics for the readout of radiation detectors

3D Integration in VLSI Circuits Katsuyuki Sakuma,2018-04-17 Currently the term 3D integration includes a wide variety of different integration methods such as 2.5 dimensional 2.5D interposer based integration 3D integrated circuits 3D ICs 3D systems in package SiP 3D heterogeneous integration and monolithic 3D ICs The goal of this book is to provide readers with an understanding of the latest challenges and issues in 3D integration TSVs are not the only technology element needed for 3D integration There are numerous other key enabling technologies required for 3D integration and the speed of the development in this emerging field is very rapid To provide readers with state of the art information on 3D integration research and technology developments each chapter has been contributed by some of the world's leading scientists and experts from academia research institutes and industry from around the globe Covers chip wafer level 3D integration technology memory stacking reconfigurable 3D and monolithic 3D IC Discusses the use of silicon interposer and organic interposer Presents architecture design and technology implementations for 3D FPGA integration Describes oxide bonding Cu/SiO₂ hybrid bonding adhesive bonding and solder bonding Addresses the issue of thermal dissipation in 3D integration

Electrical Design of Through Silicon Via Manho Lee,Jun So Pak,Joungho Kim,2014-05-11 Through Silicon Via TSV is a key technology for realizing three dimensional integrated circuits 3D ICs for future high performance and low power systems with small form factors This book covers both qualitative and quantitative approaches to give insights of modeling TSV in a various viewpoints such as signal integrity power integrity and thermal integrity Most of the analysis in this book includes simulations numerical modelings and measurements for verification The author and co authors in each chapter have studied deep into TSV for many years and the accumulated technical know hows and tips for related subjects are comprehensively covered

Silicon Photonics for High-Performance Computing and Beyond Mahdi Nikdast,Sudeep Pasricha,Gabriela Nicolescu,Ashkan Seyedi,Di Liang,2021-11-16 Silicon photonics is beginning to play an important role in driving innovations in communication and computation for an increasing number of applications from health care and biomedical sensors to autonomous driving datacenter networking and security In recent years there has been a significant amount of effort in industry and academia to innovate design develop analyze optimize and fabricate systems employing silicon photonics shaping the future of not only Datacom and telecom technology but also high performance computing and emerging computing paradigms such as optical computing and artificial intelligence Different from existing

books in this area Silicon Photonics for High Performance Computing and Beyond presents a comprehensive overview of the current state of the art technology and research achievements in applying silicon photonics for communication and computation It focuses on various design development and integration challenges reviews the latest advances spanning materials devices circuits systems and applications Technical topics discussed in the book include Requirements and the latest advances in high performance computing systems Device and system level challenges and latest improvements to deploy silicon photonics in computing systems Novel design solutions and design automation techniques for silicon photonic integrated circuits Novel materials devices and photonic integrated circuits on silicon Emerging computing technologies and applications based on silicon photonics Silicon Photonics for High Performance Computing and Beyond presents a compilation of 19 outstanding contributions from academic and industry pioneers in the field The selected contributions present insightful discussions and innovative approaches to understand current and future bottlenecks in high performance computing systems and traditional computing platforms and the promise of silicon photonics to address those challenges It is ideal for researchers and engineers working in the photonics electrical and computer engineering industries as well as academic researchers and graduate students M S and Ph D in computer science and engineering electronic and electrical engineering applied physics photonics and optics

Nanoelectronics for Next-Generation Integrated Circuits Rohit Dhiman,2022-11-23 The incessant scaling of complementary metal oxide semiconductor CMOS technology has resulted in significant performance improvements in very large scale integration VLSI design techniques and system architectures This trend is expected to continue in the future but this requires breakthroughs in the design of nano CMOS and post CMOS technologies Nanoelectronics refers to the possible future technologies beyond conventional CMOS scaling limits This volume addresses the current state of the art nanoelectronic technologies and presents potential options for next generation integrated circuits Nanoelectronics for Next generation Integrated Circuits is a useful reference guide for researchers engineers and advanced students working on the frontier of the design and modeling of nanoelectronic devices and their integration aspects with future CMOS circuits This comprehensive volume eloquently presents the design methodologies for spintronics memories quantum dot cellular automata and post CMOS FETs including applications in emerging integrated circuit technologies

Semiconductor Manufacturing Handbook 2E (PB) Hwaiyu Geng,2017-10-06 Thoroughly Revised State of the Art Semiconductor Design Manufacturing and Operations Information Written by 70 international experts and reviewed by a seasoned technical advisory board this fully updated resource clearly explains the cutting edge processes used in the design and fabrication of IC chips MEMS sensors and other electronic devices Semiconductor Manufacturing Handbook Second Edition covers the emerging technologies that enable the Internet of Things the Industrial Internet of Things data analytics artificial intelligence augmented reality and smart manufacturing You will get complete details on semiconductor fundamentals front and back end processes nanotechnology photovoltaics gases and chemicals fab yield and

operations and facilities Nanotechnology and microsystems manufacturing FinFET and nanoscale silicide formation Physical design for high performance low power 3D circuits Epitaxial anneals RTP and oxidation Microlithography etching and ion implantations Physical chemical electrochemical and atomic layer vapor deposition Chemical mechanical planarization Atomic force metrology Packaging bonding and interconnects Flexible hybrid electronics Flat panel flexible display electronics and photovoltaics Gas distribution systems Ultrapure water and filtration Process chemicals handling and abatement Chemical and slurry handling systems Yield management CIM and factory automation Manufacturing execution systems Advanced process control Airborne molecular contamination ESD controls in clean room environments Vacuum systems and RF plasma systems IC manufacturing parts cleaning technology Vibration and noise design And much more

A Synergistic Framework for Hardware IP Privacy and Integrity Protection Meng Li, David Z. Pan, 2020-04-11 This book proposes a synergistic framework to help IP vendors to protect hardware IP privacy and integrity from design optimization and evaluation perspectives The proposed framework consists of five interacting components that directly target at the primary IP violations All the five algorithms are developed based on rigorous mathematical modeling for primary IP violations and focus on different stages of IC design which can be combined to provide a formal security guarantee

Integrated Interconnect Technologies for 3D Nanoelectronic Systems Muhannad S. Bakir, James D. Meindl, 2009 This cutting edge book on off chip technologies puts the hottest breakthroughs in high density compliant electrical interconnects nanophotonics and microfluidics at your fingertips integrating the full range of mathematics physics and technology issues together in a single comprehensive source You get full details on state of the art I/O interconnects and packaging including mechanically compliant I/O approaches fabrication and assembly followed by the latest advances and applications in power delivery design analysis and modeling The book explores interconnect structures materials and packages for achieving high bandwidth off chip electrical communication including optical interconnects and chip to chip signaling approaches and brings you up to speed on CMOS integrated optical devices 3D integration wafer stacking technology and through wafer interconnects

[3D Interconnect Architectures for Heterogeneous Technologies](#) Lennart Bamberg, Jan Moritz Joseph, Alberto García-Ortiz, Thilo Pionteck, 2022-06-27 This book describes the first comprehensive approach to the optimization of interconnect architectures in 3D systems on chips SoCs specially addressing the challenges and opportunities arising from heterogeneous integration Readers learn about the physical implications of using heterogeneous 3D technologies for SoC integration while also learning to maximize the 3D technology gains through a physical effect aware architecture design The book provides a deep theoretical background covering all abstraction levels needed to research and architect tomorrow's 3D integrated circuits an extensive set of optimization methods for power performance area and yield as well as an open source optimization and simulation framework for fast exploration of novel designs

Technology Computer Aided Design for Si, SiGe and GaAs Integrated Circuits G.A. Armstrong, C.K.

Maiti,2007-11-30 The first book to deal with a broad spectrum of process and device design and modeling issues related to semiconductor devices bridging the gap between device modelling and process design using TCAD Presents a comprehensive perspective of emerging fields and covers topics ranging from materials to fabrication devices modelling and applications Aimed at research and development engineers and scientists involved in microelectronics technology and device design via Technology CAD and TCAD engineers and developers *Encyclopedia Of Thermal Packaging, Set 2: Thermal Packaging Tools (A 4-volume Set)* ,2014-10-23 remove This Encyclopedia comes in 3 sets To check out Set 1 and Set 3 please visit Set 1 Thermal Packaging Techniques and Set 3 Thermal Packaging Applications remove Thermal and mechanical packaging the enabling technologies for the physical implementation of electronic systems are responsible for much of the progress in miniaturization reliability and functional density achieved by electronic microelectronic and nanoelectronic products during the past 50 years The inherent inefficiency of electronic devices and their sensitivity to heat have placed thermal packaging on the critical path of nearly every product development effort in traditional as well as emerging electronic product categories Successful thermal packaging is the key differentiator in electronic products as diverse as supercomputers and cell phones and continues to be of pivotal importance in the refinement of traditional products and in the development of products for new applications The Encyclopedia of Thermal Packaging compiled in four multi volume sets Set 1 Thermal Packaging Techniques Set 2 Thermal Packaging Tools Set 3 Thermal Packaging Applications and Set 4 Thermal Packaging Configurations will provide a comprehensive one stop treatment of the techniques tools applications and configurations of electronic thermal packaging Each of the author written sets presents the accumulated wisdom and shared perspectives of a few luminaries in the thermal management of electronics Set 2 Thermal Packaging ToolsThe second set in the encyclopedia Thermal Packaging Tools includes volumes dedicated to thermal design of data centers techniques and models for the design and optimization of heat sinks the development and use of reduced order compact thermal models of electronic components a database of critical material thermal properties and a comprehensive exploration of thermally informed electronic design The numerical and analytical techniques described in these volumes are among the primary tools used by thermal packaging practitioners and researchers to accelerate product and system development and achieve correct by design thermal packaging solutions The four sets in the Encyclopedia of Thermal Packaging will provide the novice and student with a complete reference for a quick ascent on the thermal packaging learning curve the practitioner with a validated set of techniques and tools to face every challenge and researchers with a clear definition of the state of the art and emerging needs to guide their future efforts This encyclopedia will thus be of great interest to packaging engineers electronic product development engineers and product managers as well as to researchers in thermal management of electronic and photonic components and systems and most beneficial to undergraduate and graduate students studying mechanical electrical and electronic engineering From 2D to 3D Photonic Integrated Circuits Yasha Yi,2025-06-12 The integration of photonics and

electronics has transformed the landscape of modern technology At the forefront of this revolution is the development of Photonic Integrated Circuits PICs Historically rooted in the traditional 2 D fabrication processes inherited from electronic Integrated Circuits PICs shifted to 3 D configurations introducing new design philosophies that impact scalability efficiency and performance This convergence of electronic and photonic circuits presents unique challenges and great opportunities This book provides an introduction to photonic integrated circuits and the transition from 2D to 3D PICs It then describes design and fabrication techniques of 3D PICs and related challenges and solutions Finally applications of 3D photonics emerging technologies and industry outlook are also discussed

Wireless Radio-Frequency Standards and System

Design: Advanced Techniques Cornetta, Gianluca,Santos, David J.,Vazquez, Jose Manuel,2012-01-31 Radio frequency RF integrated circuits in CMOS technology are gaining increasing popularity in the commercial world and CMOS technology has become the dominant technology for applications such as GPS receivers GSM cellular transceivers wireless LAN and wireless short range personal area networks based on IEEE 802 15 1 Bluetooth or IEEE 802 15 4 ZigBee standards Furthermore the increasing interest in wireless technologies and the widespread of wireless communications has prompted an ever increasing demand for radio frequency transceivers Wireless Radio Frequency Standards and System Design Advanced Techniques provides perspectives on radio frequency circuit and systems design covering recent topics and developments in the RF area Exploring topics such as LNA linearization behavioral modeling and co simulation of analog and mixed signal complex blocks for RF applications integrated passive devices for RF ICs and baseband design techniques and wireless standards this is a comprehensive reference for students as well as practicing professionals

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